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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I²C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	24
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 4x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VQFN Exposed Pad
Supplier Device Package	32-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32g200f64g-e-qfn32

2. Ordering Information

The following table shows the available EFM32G devices.

Table 2.1. Ordering Information

Ordering Code	Flash (kB)	RAM (kB)	Max Speed (MHz)	Supply Voltage (V)	Temperature (°C)	Package
EFM32G200F16G-E-QFN32	16	8	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G200F32G-E-QFN32	32	8	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G200F64G-E-QFN32	64	16	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G210F128G-E-QFN32	128	16	32	1.98 - 3.8	-40 - 85	QFN32
EFM32G222F32G-E-QFP48	32	8	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G222F64G-E-QFP48	64	16	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G222F128G-E-QFP48	128	16	32	1.98 - 3.8	-40 - 85	TQFP48
EFM32G230F32G-E-QFN64	32	8	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G230F64G-E-QFN64	64	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G230F128G-E-QFN64	128	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G232F32G-E-QFP64	32	8	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G232F64G-E-QFP64	64	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G232F128G-E-QFP64	128	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G280F32G-E-QFP100	32	8	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G280F64G-E-QFP100	64	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G280F128G-E-QFP100	128	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G290F32G-E-BGA112	32	8	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G290F64G-E-BGA112	64	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G290F128G-E-BGA112	128	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G840F32G-E-QFN64	32	8	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G840F64G-E-QFN64	64	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G840F128G-E-QFN64	128	16	32	1.98 - 3.8	-40 - 85	QFN64
EFM32G842F32G-E-QFP64	32	8	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G842F64G-E-QFP64	64	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G842F128G-E-QFP64	128	16	32	1.98 - 3.8	-40 - 85	TQFP64
EFM32G880F32G-E-QFP100	32	8	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G880F64G-E-QFP100	64	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G880F128G-E-QFP100	128	16	32	1.98 - 3.8	-40 - 85	LQFP100
EFM32G890F32G-E-BGA112	32	8	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G890F64G-E-BGA112	64	16	32	1.98 - 3.8	-40 - 85	BGA112
EFM32G890F128G-E-BGA112	128	16	32	1.98 - 3.8	-40 - 85	BGA112

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3.1.4 Direct Memory Access Controller (DMA)

The Direct Memory Access (DMA) controller performs memory operations independently of the CPU. This has the benefit of reducing the energy consumption and the workload of the CPU, and enables the system to stay in low energy modes when moving for instance data from the USART to RAM or from the External Bus Interface to a PWM-generating timer. The DMA controller uses the PL230 µDMA controller licensed from ARM.

3.1.5 Reset Management Unit (RMU)

The RMU is responsible for handling the reset functionality of the EFM32G.

3.1.6 Energy Management Unit (EMU)

The Energy Management Unit (EMU) manage all the low energy modes (EM) in EFM32G microcontrollers. Each energy mode manages if the CPU and the various peripherals are available. The EMU can also be used to turn off the power to unused SRAM blocks.

3.1.7 Clock Management Unit (CMU)

The Clock Management Unit (CMU) is responsible for controlling the oscillators and clocks on-board the EFM32G. The CMU provides the capability to turn on and off the clock on an individual basis to all peripheral modules in addition to enable/disable and configure the available oscillators. The high degree of flexibility enables software to minimize energy consumption in any specific application by not wasting power on peripherals and oscillators that are inactive.

3.1.8 Watchdog (WDOG)

The purpose of the watchdog timer is to generate a reset in case of a system failure, to increase application reliability. The failure may e.g. be caused by an external event, such as an ESD pulse, or by a software failure.

3.1.9 Peripheral Reflex System (PRS)

The Peripheral Reflex System (PRS) system is a network which lets the different peripheral module communicate directly with each other without involving the CPU. Peripheral modules which send out Reflex signals are called producers. The PRS routes these reflex signals to consumer peripherals which apply actions depending on the data received. The format for the Reflex signals is not given, but edge triggers and other functionality can be applied by the PRS.

3.1.10 External Bus Interface (EBI)

The External Bus Interface provides access to external parallel interface devices such as SRAM, FLASH, ADCs and LCDs. The interface is memory mapped into the address bus of the Cortex-M3. This enables seamless access from software without manually manipulating the IO settings each time a read or write is performed. The data and address lines are multiplexed in order to reduce the number of pins required to interface the external devices. The timing is adjustable to meet specifications of the external devices. The interface is limited to asynchronous devices.

3.1.11 Inter-Integrated Circuit Interface (I2C)

The I²C module provides an interface between the MCU and a serial I²C-bus. It is capable of acting as both a master and a slave, and supports multi-master buses. Both standard-mode, fast-mode and fastmode plus speeds are supported, allowing transmission rates all the way from 10 kbit/s up to 1 Mbit/s. Slave arbitration and timeouts are also provided to allow implementation of an SMBus compliant system. The interface provided to software by the I²C module, allows both fine-grained control of the transmission process and close to automatic transfers. Automatic recognition of slave addresses is provided in all energy modes.

3.1.12 Universal Synchronous/Asynchronous Receiver/Transmitter (USART)

The Universal Synchronous Asynchronous serial Receiver and Transmitter (USART) is a very flexible serial I/O module. It supports full duplex asynchronous UART communication as well as RS-485, SPI, MicroWire and 3-wire. It can also interface with ISO7816 Smart-Cards, and IrDA devices.

3.1.13 Pre-Programmed USB/UART Bootloader

The bootloader presented in application note AN0003 is pre-programmed in the device at factory. Autobaud and destructive write are supported. The autobaud feature, interface and commands are described further in the application note.

3.1.24 Advanced Encryption Standard Accelerator (AES)

The AES accelerator performs AES encryption and decryption with 128-bit or 256-bit keys. Encrypting or decrypting one 128-bit data block takes 52 HFCORECLK cycles with 128-bit keys and 75 HFCORECLK cycles with 256-bit keys. The AES module is an AHB slave which enables efficient access to the data and key registers. All write accesses to the AES module must be 32-bit operations, i.e. 8- or 16-bit operations are not supported.

3.1.25 General Purpose Input/Output (GPIO)

General Purpose Input/Output (GPIO) pins are organized into ports with up to 16 pins each. These pins can individually be configured as either an output or input. More advanced configurations like open-drain, filtering and drive strength can also be configured individually for the pins. The GPIO pins can also be overridden by peripheral pin connections, like Timer PWM outputs or USART communication, which can be routed to several locations on the device. The GPIO supports up to 16 asynchronous external pin interrupts, which enables interrupts from any pin on the device. Also, the input value of a pin can be routed through the Peripheral Reflex System to other peripherals.

3.1.26 Liquid Crystal Display Driver (LCD)

The LCD driver is capable of driving a segmented LCD display with up to 4x40 segments. A voltage boost function enables it to provide the LCD display with higher voltage than the supply voltage for the device. In addition, an animation feature can run custom animations on the LCD display without any CPU intervention. The LCD driver can also remain active even in Energy Mode 2 and provides a Frame Counter interrupt that can wake-up the device on a regular basis for updating data.

3.2.4 EFM32G230

The features of the EFM32G230 is a subset of the feature set described in the EFM32G Reference Manual. The following table describes device specific implementation of the features.

Table 3.4. EFM32G230 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration	US2_TX, US2_RX, US2_CLK, US2_CS
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 8-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0]
AES	Full configuration	NA
GPIO	56 pins	Available pins are shown in Table 4.3 (p. 57)

3.2.11 EFM32G890

The features of the EFM32G890 is a subset of the feature set described in the EFM32G Reference Manual. The following table describes device specific implementation of the features.

Table 3.11. EFM32G890 Configuration Summary

Module	Configuration	Pin Connections
Cortex-M3	Full configuration	NA
DBG	Full configuration	DBG_SWCLK, DBG_SWDIO, DBG_SWO
MSC	Full configuration	NA
DMA	Full configuration	NA
RMU	Full configuration	NA
EMU	Full configuration	NA
CMU	Full configuration	CMU_OUT0, CMU_OUT1
WDOG	Full configuration	NA
PRS	Full configuration	NA
EBI	Full configuration	EBI_ARDY, EBI_ALE, EBI_WEn, EBI_REn, EBI_CS[3:0], EBI_AD[15:0]
I2C0	Full configuration	I2C0_SDA, I2C0_SCL
USART0	Full configuration with IrDA	US0_TX, US0_RX, US0_CLK, US0_CS
USART1	Full configuration	US1_TX, US1_RX, US1_CLK, US1_CS
USART2	Full configuration	US2_TX, US2_RX, US2_CLK, US2_CS
UART0	Full configuration	U0_TX, U0_RX
LEUART0	Full configuration	LEU0_TX, LEU0_RX
LEUART1	Full configuration	LEU1_TX, LEU1_RX
TIMER0	Full configuration with DTI	TIM0_CC[2:0], TIM0_CDTI[2:0]
TIMER1	Full configuration	TIM1_CC[2:0]
TIMER2	Full configuration	TIM2_CC[2:0]
RTC	Full configuration	NA
LETIMER0	Full configuration	LET0_O[1:0]
PCNT0	Full configuration, 8-bit count register	PCNT0_S[1:0]
PCNT1	Full configuration, 8-bit count register	PCNT1_S[1:0]
PCNT2	Full configuration, 8-bit count register	PCNT2_S[1:0]
ACMP0	Full configuration	ACMP0_CH[7:0], ACMP0_O
ACMP1	Full configuration	ACMP1_CH[7:0], ACMP1_O
VCMP	Full configuration	NA
ADC0	Full configuration	ADC0_CH[7:0]
DAC0	Full configuration	DAC0_OUT[1:0]
AES	Full configuration	NA
GPIO	90 pins	Available pins are shown in Table 4.3 (p. 57)

4.9.3 LFRCO

Table 4.10. LFRCO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Oscillation frequency, $V_{DD} = 3.0$ V, $T_{AMB} = 25^\circ\text{C}$	f_{LFRCO}		31.29	32.768	34.24	kHz
Startup time not including software calibration	t_{LFRCO}		—	150	—	μs
Current consumption	I_{LFRCO}		—	190	—	nA
Temperature coefficient	TC_{LFRCO}		—	± 0.02	—	%/ $^\circ\text{C}$
Supply voltage coefficient	VC_{LFRCO}		—	± 15	—	%/V
Frequency step for LSB change in TUNING value	$TUNESTEP_{LFRCO}$		—	1.5	—	%

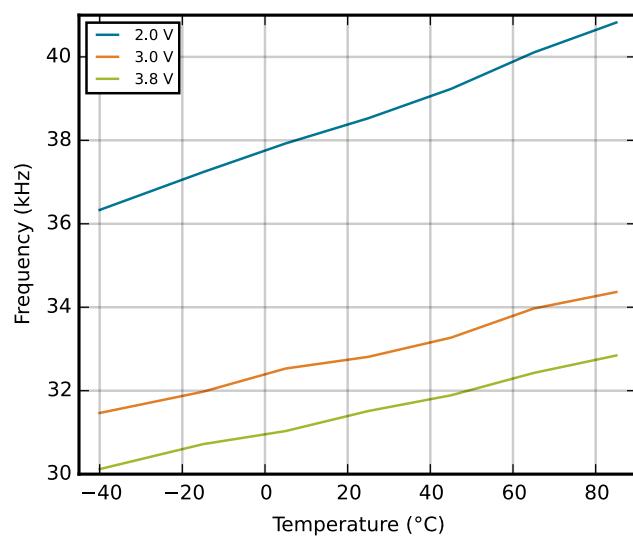
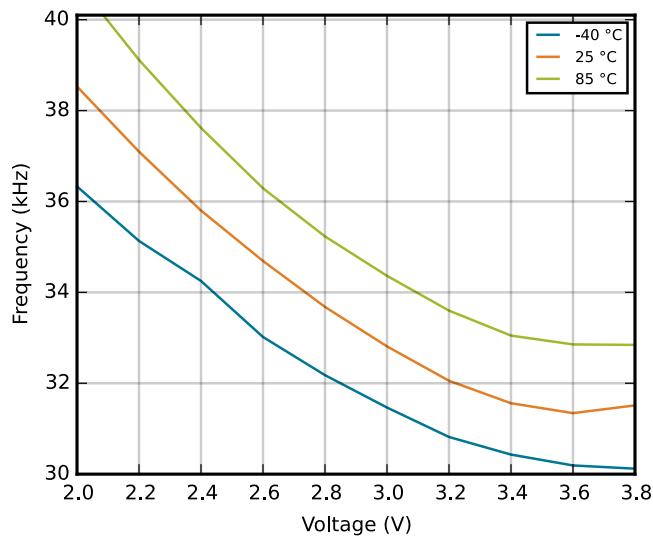


Figure 4.20. Calibrated LFRCO Frequency vs Temperature and Supply Voltage

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Spurious-Free Dynamic Range (SFDR)	SFDR _{ADC}	1 MSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	75	—	dBc
		1 MSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, single-ended, V _{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	78	—	dBc
		1 MSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	77	—	dBc
		1 MSamples/s, 12 bit, differential, V _{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	76	—	dBc
		1 MSamples/s, 12 bit, differential, 2xV _{DD} reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	68	79	—	dBc
		1 MSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 13 MHz, BIASPROG = 0xF4B	—	79	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	75	—	dBc
		200 kSamples/s, 12 bit, single-ended, V _{DD} reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	76	—	dBc
		200 kSamples/s, 12 bit, differential, internal 1.25 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, internal 2.5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	79	—	dBc
		200 kSamples/s, 12 bit, differential, 5 V reference, ADC_CLK = 7 MHz, BIASPROG = 0x747	—	78	—	dBc

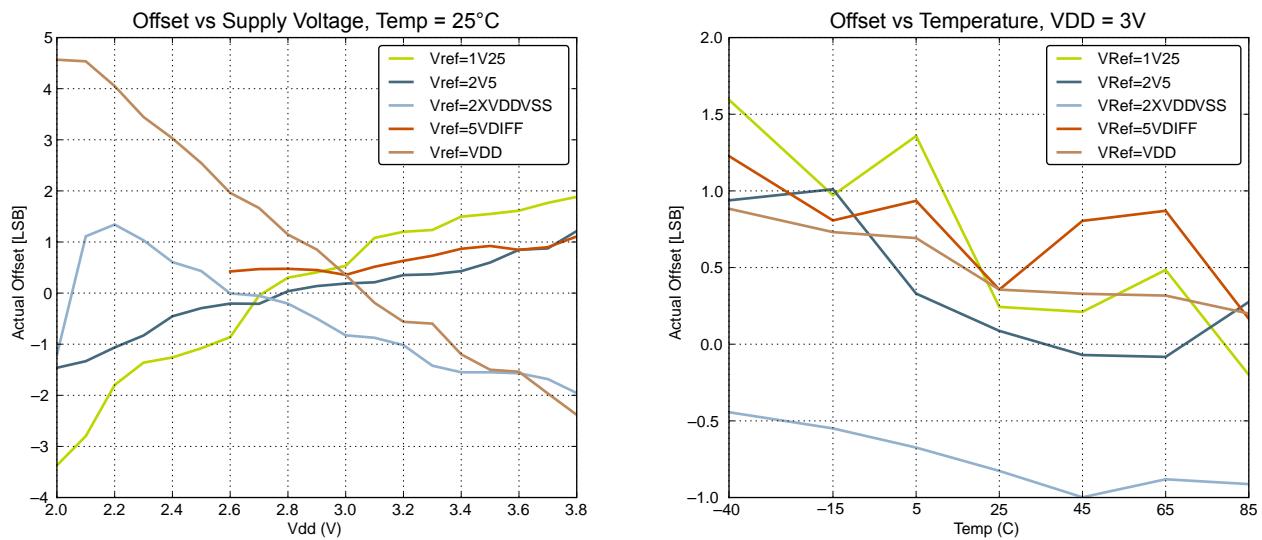


Figure 4.32. ADC Absolute Offset, Common Mode = VDD/2

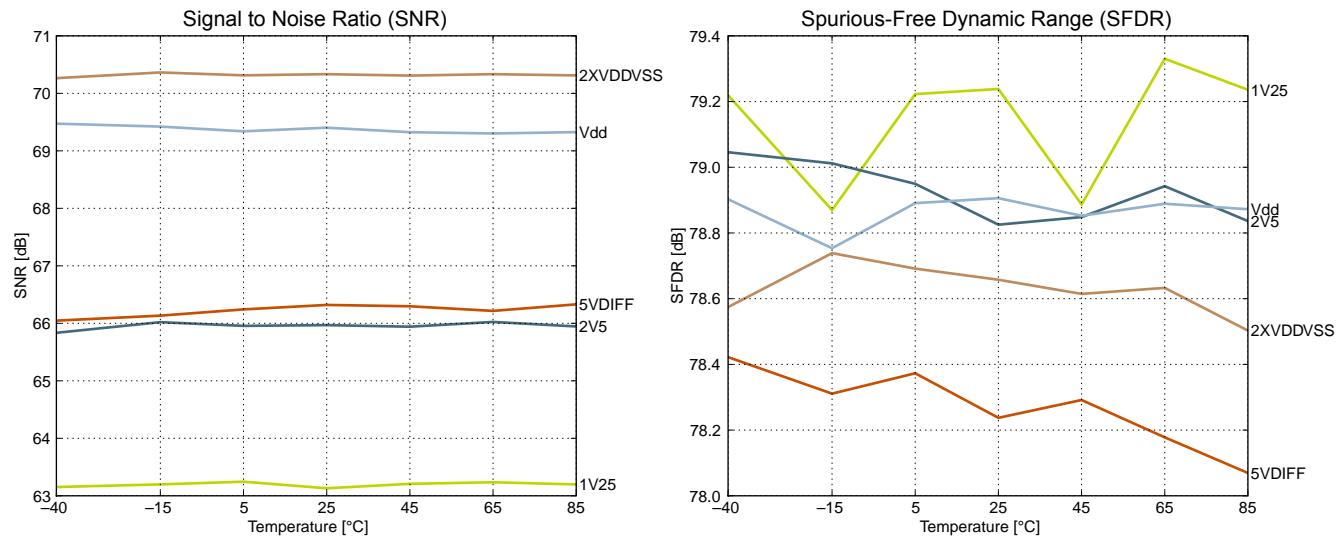


Figure 4.33. ADC Dynamic Performance vs Temperature for all ADC References, VDD = 3V

4.12 Analog Comparator (ACMP)

Table 4.16. ACMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	V _{ACMPIN}		0	—	V _{DD}	V
ACMP Common Mode voltage range	V _{ACMPCM}		0	—	V _{DD}	V
Active current	I _{ACMP}	BIASPROG=0b0000, FULL-BIAS=0 and HALFBIAS=1 in ACMPn_CTRL register	—	55	600	μA
		BIASPROG=0b1111, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	—	2.82	12	μA
		BIASPROG=0b1111, FULL-BIAS=1 and HALFBIAS=0 in ACMPn_CTRL register	—	250	520	μA
Current consumption of internal voltage reference	I _{ACMPREF}	Internal voltage reference off. Using external voltage reference	—	0	0.5	μA
		Internal voltage reference, LPREF=1	—	0.050	3	μA
		Internal voltage reference, LPREF=0	—	6	—	μA
Offset voltage	V _{ACMPOFFSET}	BIASPROG= 0b1010, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	-12	0	12	mV
ACMP hysteresis	V _{ACMPHYST}	Programmable	—	17	—	mV
Capacitive Sense Internal Resistance	R _{CSRES}	CSRESSEL=0b00 in ACMPn_INPUTSEL	—	39	—	kΩ
		CSRESSEL=0b01 in ACMPn_INPUTSEL	—	71	—	kΩ
		CSRESSEL=0b10 in ACMPn_INPUTSEL	—	104	—	kΩ
		CSRESSEL=0b11 in ACMPn_INPUTSEL	—	136	—	kΩ
Startup time	t _{ACMPSTART}		—	—	10	μs

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given in the following equation. I_{ACMPREF} is zero if an external voltage reference is used.

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$$

5.1.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32G200 and EFM32G210 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

Table 5.3. GPIO Pinout

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	—	—	—	—	—	—	—	—	—	—	—	—	—	PA2	PA1	PA0
Port B	—	PB14	PB13	—	PB11	—	—	PB8	PB7	—	—	—	—	—	—	—
Port C	PC15	PC14	PC13	—	—	—	—	—	—	—	—	—	—	—	PC1	PC0
Port D	—	—	—	—	—	—	—	—	PD7	PD6	PD5	PD4	—	—	—	—
Port E	—	—	PE13	PE12	PE11	PE10	—	—	—	—	—	—	—	—	—	—
Port F	—	—	—	—	—	—	—	—	—	—	—	—	—	PF2	PF1	PF0

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
6	PA5		TIM0_CDTI2 #0	LEU1_TX #1	
7	IOVDD_0	Digital IO power supply 0.			
8	VSS	Ground.			
9	PC0	ACMP0_CH0	PCNT0_S0IN #1	US1_TX #1	
10	PC1	ACMP0_CH1	PCNT0_S1IN #1	US1_RX #1	
11	PC2	ACMP0_CH2		US1_CLK #1	
12	PC3	ACMP0_CH3		US1_CS #1	
13	PC4	ACMP0_CH4	LETIMO_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
14	PC5	ACMP0_CH5	LETIMO_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
15	PB7	LFXTAL_P		US1_CLK #0	
16	PB8	LFXTAL_N		US1_CS #0	
17	PA8		TIM2_CC0 #0		
18	PA9		TIM2_CC1 #0		
19	PA10		TIM2_CC2 #0		
20	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.			
21	PB11	DAC0_OUT0	LETIMO_OUT0 #1		
22	VSS	Ground.			
23	AVDD_1	Analog power supply 1.			
24	PB13	HFXTAL_P		LEU0_TX #1	
25	PB14	HFXTAL_N		LEU0_RX #1	
26	IOVDD_3	Digital IO power supply 3.			
27	AVDD_0	Analog power supply 0.			
28	PD0	ADC0_CH0	PCNT2_S0IN #0	US1_TX #1	
29	PD1	ADC0_CH1	TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
30	PD2	ADC0_CH2	TIM0_CC1 #3	US1_CLK #1	
31	PD3	ADC0_CH3	TIM0_CC2 #3	US1_CS #1	
32	PD4	ADC0_CH4		LEU0_TX #0	
33	PD5	ADC0_CH5		LEU0_RX #0	
34	PD6	ADC0_CH6	LETIMO_OUT0 #0	I2C0_SDA #1	
35	PD7	ADC0_CH7	LETIMO_OUT1 #0	I2C0_SCL #1	
36	PD8				CMU_CLK1 #1
37	PC6	ACMP0_CH6		LEU1_TX #0 I2C0_SDA #2	
38	PC7	ACMP0_CH7		LEU1_RX #0 I2C0_SCL #2	

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
6	PA5		EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
7	PA6		EBI_AD15 #0		LEU1_RX #1	
8	IOVDD_0	Digital IO power supply 0.				
9	PB0			TIM1_CC0 #2		
10	PB1			TIM1_CC1 #2		
11	PB2			TIM1_CC2 #2		
12	PB3			PCNT1_S0IN #1	US2_TX #1	
13	PB4			PCNT1_S1IN #1	US2_RX #1	
14	PB5				US2_CLK #1	
15	PB6				US2_CS #1	
16	VSS	Ground.				
17	IOVDD_1	Digital IO power supply 1.				
18	PC0	ACMP0_C_H0		PCNT0_S0IN #2	US1_TX #0	
19	PC1	ACMP0_C_H1		PCNT0_S1IN #2	US1_RX #0	
20	PC2	ACMP0_C_H2			US2_TX #0	
21	PC3	ACMP0_C_H3			US2_RX #0	
22	PC4	ACMP0_C_H4		LETIMO_OUT0 #3 PCNT1_S0IN #0	US2_CLK #0	
23	PC5	ACMP0_C_H5		LETIMO_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
24	PB7	LFXTAL_P			US1_CLK #0	
25	PB8	LFXTAL_N			US1_CS #0	
26	PA7					
27	PA8			TIM2_CC0 #0		
28	PA9			TIM2_CC1 #0		
29	PA10			TIM2_CC2 #0		
30	PA11					
31	IOVDD_2	Digital IO power supply 2.				
32	VSS	Ground.				
33	PA12			TIM2_CC0 #1		
34	PA13			TIM2_CC1 #1		
35	PA14			TIM2_CC2 #1		
36	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
37	PB9					
38	PB10					
39	PB11	DAC0_OU_T0		LETIM0_OUT0 #1		
40	PB12	DAC0_OU_T1		LETIM0_OUT1 #1		
41	AVDD_1	Analog power supply 1.				
42	PB13	HFXTAL_P			LEU0_TX #1	
43	PB14	HFXTAL_N			LEU0_RX #1	
44	IOVDD_3	Digital IO power supply 3.				
45	AVDD_0	Analog power supply 0.				
46	PD0	ADC0_CH0		PCNT2_S0IN #0	US1_TX #1	
47	PD1	ADC0_CH1		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
48	PD2	ADC0_CH2		TIM0_CC1 #3	US1_CLK #1	
49	PD3	ADC0_CH3		TIM0_CC2 #3	US1_CS #1	
50	PD4	ADC0_CH4			LEU0_TX #0	
51	PD5	ADC0_CH5			LEU0_RX #0	
52	PD6	ADC0_CH6		LETIM0_OUT0 #0	I2C0_SDA #1	
53	PD7	ADC0_CH7		LETIM0_OUT1 #0	I2C0_SCL #1	
54	PD8					CMU_CLK1 #1
55	PC6	ACMP0_C_H6			LEU1_TX #0 I2C0_SDA #2	
56	PC7	ACMP0_C_H7			LEU1_RX #0 I2C0_SCL #2	
57	VDD_DREG	Power supply for on-chip voltage regulator.				
58	VSS	Ground.				
59	DECOPPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOPPLE}$ is required at this pin.				
60	PE0			PCNT0_S0IN #1	U0_TX #1	
61	PE1			PCNT0_S1IN #1	U0_RX #1	
62	PE2					ACMP0_O #1

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
28	PA9	LCD_SEG_37		TIM2_CC1 #0		
29	PA10	LCD_SEG_38		TIM2_CC2 #0		
30	PA11	LCD_SEG_39				
31	IOVDD_2	Digital IO power supply 2.				
32	VSS	Ground.				
33	PA12	LCD_BCA_P_P		TIM2_CC0 #1		
34	PA13	LCD_BCA_P_N		TIM2_CC1 #1		
35	PA14	LCD_BEX_T		TIM2_CC2 #1		
36	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
37	PB9					
38	PB10					
39	PB11	DAC0_OU_T0		LETIM0_OUT0 #1		
40	PB12	DAC0_OU_T1		LETIM0_OUT1 #1		
41	AVDD_1	Analog power supply 1.				
42	PB13	HFXTAL_P			LEU0_TX #1	
43	PB14	HFXTAL_N			LEU0_RX #1	
44	IOVDD_3	Digital IO power supply 3.				
45	AVDD_0	Analog power supply 0.				
46	PD0	ADC0_CH_0		PCNT2_S0IN #0	US1_TX #1	
47	PD1	ADC0_CH_1		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
48	PD2	ADC0_CH_2		TIM0_CC1 #3	US1_CLK #1	
49	PD3	ADC0_CH_3		TIM0_CC2 #3	US1_CS #1	
50	PD4	ADC0_CH_4			LEU0_TX #0	
51	PD5	ADC0_CH_5			LEU0_RX #0	
52	PD6	ADC0_CH_6		LETIM0_OUT0 #0	I2C0_SDA #1	

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
53	PD7	ADC0_CH7		LETIM0_OUT1 #0	I2C0_SCL #1	
54	PD8					CMU_CLK1 #1
55	PC6	ACMP0_C_H6			LEU1_TX #0 I2C0_SDA #2	
56	PC7	ACMP0_C_H7			LEU1_RX #0 I2C0_SCL #2	
57	VDD_DREG	Power supply for on-chip voltage regulator.				
58	VSS	Ground.				
59	DECOPLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{DECOPLE}$ is required at this pin.				
60	PE0			PCNT0_S0IN #1	U0_TX #1	
61	PE1			PCNT0_S1IN #1	U0_RX #1	
62	PE2					ACMP0_O #1
63	PE3					ACMP1_O #1
64	PE4	LCD_COM0			US0_CS #1	
65	PE5	LCD_COM1			US0_CLK #1	
66	PE6	LCD_COM2			US0_RX #1	
67	PE7	LCD_COM3			US0_TX #1	
68	PC8	ACMP1_C_H0		TIM2_CC0 #2	US0_CS #2	
69	PC9	ACMP1_C_H1		TIM2_CC1 #2	US0_CLK #2	
70	PC10	ACMP1_C_H2		TIM2_CC2 #2	US0_RX #2	
71	PC11	ACMP1_C_H3			US0_TX #2	
72	PC12	ACMP1_C_H4				CMU_CLK0 #1
73	PC13	ACMP1_C_H5		TIM0_CDTI0 #1/3 TIM1_CC0 #0 PCNT0_S0IN #0		
74	PC14	ACMP1_C_H6		TIM0_CDTI1 #1/3 TIM1_CC1 #0 PCNT0_S1IN #0	U0_TX #3	
75	PC15	ACMP1_C_H7		TIM0_CDTI2 #1/3 TIM1_CC2 #0	U0_RX #3	DBG_SWO #1
76	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTIO	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.

7.3 LQFP100 Package Marking

In the illustration below package fields and position are shown.

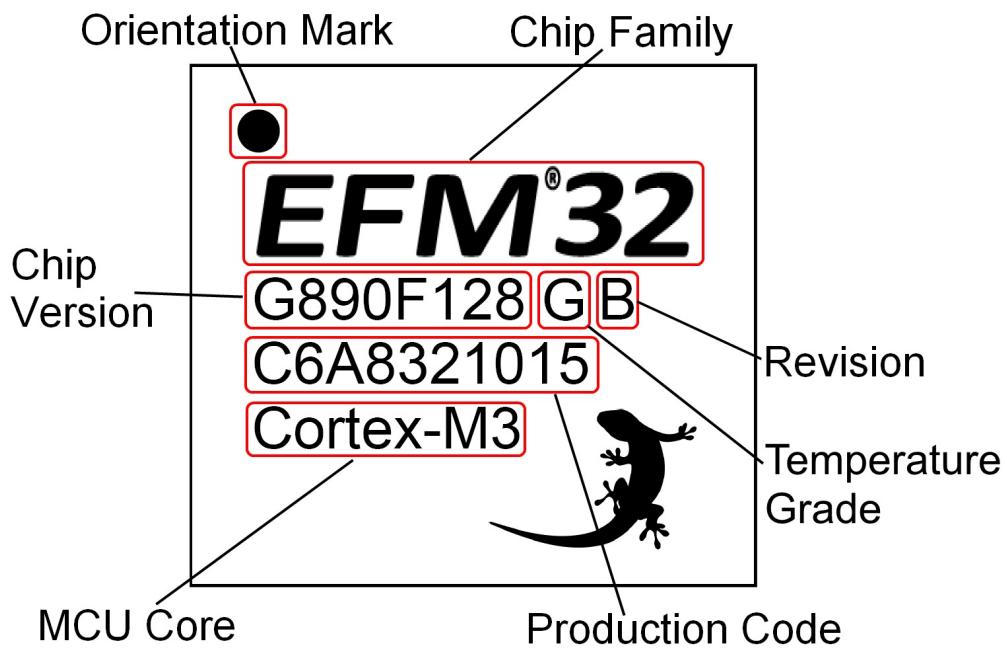


Figure 7.5. Example Chip Marking (Top View)

12. Chip Revision, Solder Information, Errata

12.1 Chip Revision

The revision of a chip can be determined from the "Revision" field in the package marking.

12.2 Soldering Information

The latest IPC/JEDEC J-STD-020 recommendations for Pb-Free reflow soldering should be followed.

12.3 Errata

Please see the errata document for description and resolution of device errata. This document is available in Simplicity Studio and online at: <http://www.silabs.com/support/pages/document-library.aspx?p=MCUs--32-bit>

13.15 Revision 0.90

This revision applies the following devices:

- EFM32G222

Initial preliminary revision, April 14th, 2011

This revision applies the following devices:

- EFM32G232
- EFM32G842

Initial preliminary revision, June 30th, 2011

13.16 Revision 0.85

February 19th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Renamed DBG_SWV pin to DBG_SWO.

13.17 Revision 0.84

February 11th, 2010

This revision applies the following devices:

- EFM32G230
- EFM32G840

Corrected pinout tables.

13.18 Revision 0.83

January 25th, 2010

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Updated errata section.

Specified flash word width in Flash Electrical Characteristics.

Added Capacitive Sense Internal Resistor values in ACMP Electrical Characteristics.